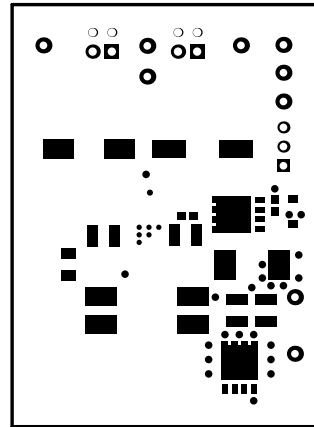
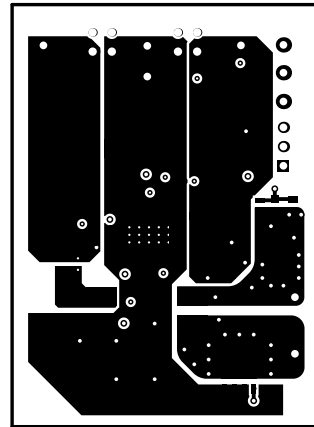


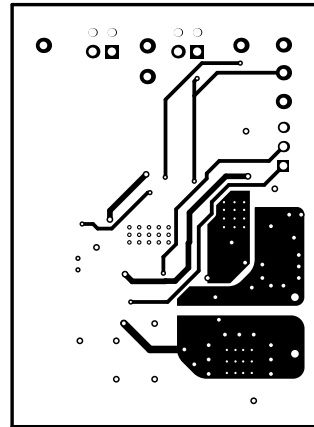
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30232	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 10/11/2017 13:48:05	TEXAS INSTRUMENTS	



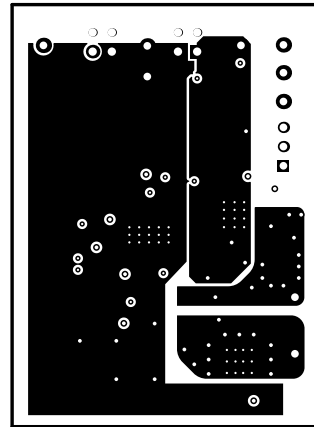
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30232	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 10/11/2017 13:48:06	TEXAS INSTRUMENTS	



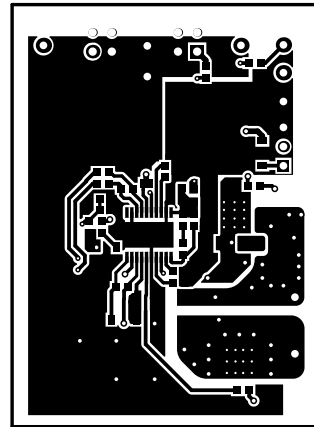
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30232	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 10/11/2017 13:48:07	TEXAS INSTRUMENTS	



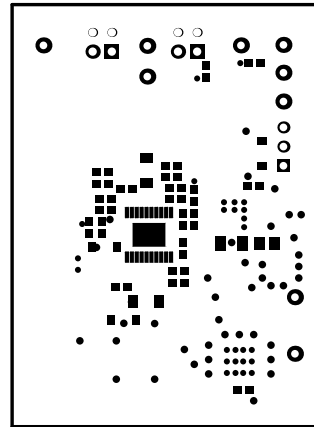
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30232	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 1	GENERATED : 10/11/2017 13:48:08	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30232	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: N/A		
PLOT NAME = Signal Layer 2	GENERATED : 10/11/2017 13:48:09	TEXAS INSTRUMENTS	



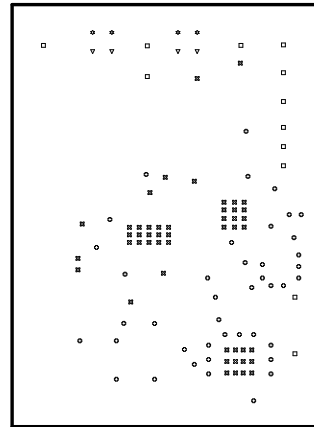
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30232	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 10/11/2017 13:48:10	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30232	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 10/11/2017 13:48:11	TEXAS INSTRUMENTS	



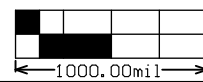
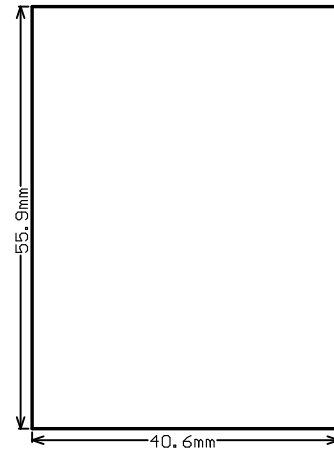




Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Tolerance
⊗	4	43.31mil (1.100mm)	NPTH	Round	Top Layer - Bottom Layer	
⊗	49	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	42	19.68mil (0.500mm)	PTH	Round	Top Layer - Bottom Layer	
□	12	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
	111 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30232	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 10/11/2017 13:48:12	TEXAS INSTRUMENTS	

10/11/2017 13:48:14



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP30232	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 10/11/2017 13:48:14	TEXAS INSTRUMENTS	

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